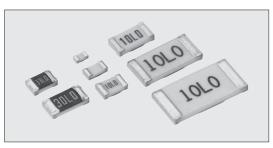
THICK FILM (LOW RESISTANCE)



UR73 ■ Low Resistance Flat Chip Resistors (Low T.C.R.)



Coating color: Indigo

Features

- Current detecting resistors for power supplies, motor circuits, etc.
- Low resistance $(100 \, \text{m} \, \Omega \, \text{or} \, \text{under})$ and high accuracy resistors ($\pm 1 \, \%$) for current detection.
- High reliability and performance with T.C.R. $+100\times10^{-6}$ /K
- Suitable for flow and reflow solderings.
- Products meet EU-RoHS requirements.

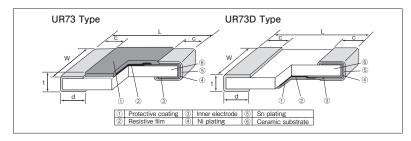
Applications

 Computers, HDDs, Cellular-telephones, Power supplies, and Motor circuits, etc.

■Reference Standards

IEC 60115-8 JIS C 5201-8

■ Construction



Dimensions

Type	Resistance range	Resistance range (mm)					Weight(g)
(Inch Size Code)	(Ω)	L	W	С	d	t	(1000pcs)
UR73D 1E(0402)	24m~100m	1.0+0.1	0.5 ^{+0.1} _{-0.05}	0.25±0.1	0.3±0.1	0.4±0.05	0.72
UR73D 1J (0603)	10m~27m	1.6±0.2	0.8+0.15	0.35±0.1	0.55±0.1	0.5±0.1	2.84
	30m~100m	1.0±0.2			0.35±0.1	0.5±0.1	
UR73D 2A(0805)	10m~16m	2.0±0.2	1.25±0.2	0.4±0.2	0.6±0.2	0.55±0.1	5.74
	18m~30m	2.0±0.2			0.5±0.2	0.55±0.1	
UR73 2A (0805)	33m~100m	2.0 ± 0.2	1.25±0.2	0.4±0.2	0.3+0.2	0.55±0.1	5.60
UR73D 2B(1206)	10m~16m	3.2+0.2	1.6±0.2	0.5±0.2	1.0±0.2	0.6±0.1	11.12
OH/3D 2B(1200)	18m~27m	5.2 ± 0.2			0.8±0.2	0.0 ± 0.1	
UR73 2B(1206)	30m~100m	3.2 ± 0.2	1.6±0.2	0.5±0.3	0.4+0.2	0.6±0.1	10.09
UR73D 2H (2010)	10m~30m	5.0+0.2	2.5±0.2	0.65±0.3	1.6±0.3	0.65±0.1	29.80
	33m~100m	3.0 ± 0.2			0.65±0.3	0.05±0.1	
UR73D 3A(2512)	10m~30m	6.3±0.2	3.1±0.2	0.8±0.3	2.0±0.3	0.6±0.1	47.69
UN/3D 3A(2512)	33m~100m	0.3±0.2			0.8±0.3	0.0 ±0.1	47.09

■Type Designation



Resistance Value (Ω)	4 digits				
10m~91m	10L0~91L0				
0.1	R100				

Contact us when you have control request for environmental hazardous material other than the substance specified by EU-RoHS. For further information or taping, please refer to APPENDIX C on the back pages.

■Ratings

Туре	Power				Resistance Range (Ω)	Resistance	Operating Temp.	Taping & Q'ty/Reel (pcs)		
Туре	Rating	Temp.	Part Temp.	(×10 ⁻⁶ /K)	E24 & 25m, 50m*1	Tolerance	Range	TP	TD	TE
UR73D 1E*2	0.125W	70°C		±500	24m~27m		-55°C∼+125°C	10.000	_	
OH/3D IE	0.125	700	_	±100	30m~100m			10,000		_
			80°C	±300	10m~27m			_	5,000	_
UR73D 1J	UR73D 1J 0.25W 70	70°C		±200	30m~43m					
				±100	47m~100m					
UR73D 2A	0.33W	70°C	90℃	±250	10m~30m			_	5,000	_
11070.04	UR73 2A 0.33W	70°C	100℃	±250	33m~43m	F: ±1%		_	5,000	_
UH/3 ZA				±100	47m~100m					
UR73D 2B	0.5W	70°C	85°C	±200	10m~27m			_	5,000	_
UR73 2B	200	70°C	85°C —	±200	30m~43m				F 000	
UR73 2B 0.5W	700	850	±100	47m~100m				5,000	_	
UR73D 2H	0.75W	70°C	90°C	±250	10m~30m					4.000
UR/3D 2H	UR/3D ZH 0.75W	/00		±100	33m~100m				_	4,000
LIDZOD OA	UR73D 3A 1W 70°C	95℃	±250	10m~30m					4.000	
UH/3D 3A		700	700 950	±100	33m~100m			, – I	_	4,000

Rated voltage=\sqrt{Power Rating \times Resistance value}

Malfunction or failure of the products in such applications may cause loss of human life or serious damage.

 $\%1~25 \mathrm{m}\,\Omega$ and $50 \mathrm{m}\,\Omega$ are available.

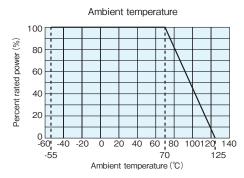
%1 25m11 and 50m11 are available.
%2 Please inquire before use.

If any questions arise whether to use the "Rated Ambient Temperature" or the "Rated Terminal Part Temperature" in your usage conditions, please give priority to the "Rated Terminal Part Temperature".

For more details, please refer to "Introduction of the derating curves based on the terminal part temperature" on the beginning of our catalog.



■ Derating Curve

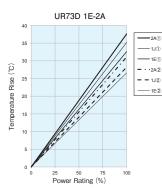


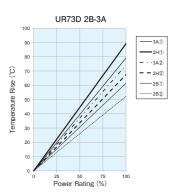
For resistors operated at an ambient temperature of $70^{\circ}\mathrm{C}$ or higher, the power shall be derated in accordance with the above derating curve.

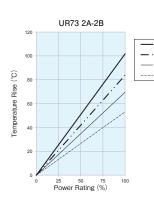
Terminal part temperature 100 Percent rated power (%) D1J/0.25W(80°C) 2B/0.5W, D2B/0.5W(85°C) 60 D2A/0.33W, D2H/0.75W(90°C) D3A/1W(95°C) 40 2A/0.33W(100°C) 20 -60<u>!</u> 20 80 100120 140 -40 -20 0 40 85 90 95 -55 125 Terminal part temperature (°C)

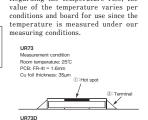
When the terminal part temperature of the resistor exceeds the rated terminal part temperature shown above, the power shall be derated according to the derating curve. **Please refer to "Introduction of the derating curves based on the terminal part temperature" on the beginning of our catalog before use.

■Temperature Rise





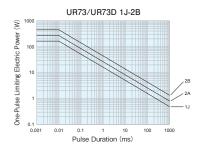


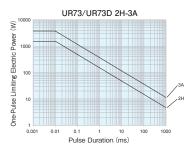


Regarding the temperature rise, the

Room temperature: 25°C PCB: FR-44 = 16'mm Cu foil thickness: 35'µm ①: Hot spot

■One-Pulse Limiting Electric Power





Please ask us about the resistance characteristic of continuous applied pulse. The pulse endurance values are not assured values, so be sure to check the products on actual equipment when you use them.

■Performance

Test Items	Performance Requirements	ΔR± (%+0.005Ω)	Took Makhada		
rest items	Limit	Typical	Test Methods		
Resistance	Within specified tolerance	_	25°C		
T.C.R.	Within specified T.C.R.	_	+25°C/-55°C and +25°C/+125°C		
Overload (Short time)	2	0.5	Rated voltage × 2.5 for 5s		
Resistance to soldering heat	1	0.3	260°C±5°C, 10s±1s		
Rapid change of temperature	1	0.5	-55°C (30min.) /+125°C (30min.) 100 cycles		
Moisture resistance	2	1	40°C±2°C, 90%~95%RH, 1000h 1.5h ON/0.5h OFF cycle		
Endurance at 70°C or rated terminal part temperature	2	1	70°C±2°C or rated terminal part temperature ±2°C 1000h 1.5h ON/0.5h OFF cycle		
High temperature exposure	1	0.3	+125°C, 1000h		

■Precautions for Use

- The substrate of chip resistors is alumina. Cracks may occur at the connection of solder (solder fillet portion) due to the difference of the coefficient of thermal expansion from a mounting board when heat stress like heat cycle, etc. are repeatedly given to them. Care should be taken to the occurrence of the cracks when the change in ambient temperature or ON /OFF of load is repeated, especially when large types of 2H/3A which have large thermal expansion and also self heating. By general temperature cycle test using glass-epoxy(FR-4) boards under the maximum/minimum temperatures of operating temperature range, the crack does not occur easily in the types of 1E~2B, but the crack tends to occur in the types of 2H/3A. The occurrence of the crack by heat stress may be influenced by the size of a pad, solder volume, heat radiation of mounting board etc., so please pay careful attention to designing when a big change in ambient temperature and conditions for use like ON/OFF of load can be assumed.
- In the resistance values of 50m Ω or under, the resistance value after soldering may change depending on the size of pad pattern or solder amount. Make sure the effect of decline/increase of resistance value before designing.